

General Description

The WST05P06 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent R_{DSON} and gate charge for most of the synchronous buck converter applications .

The WST05P06 meet the RoHS and Green Product requirement, with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

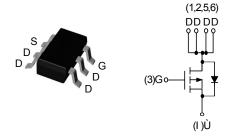
Product Summery

BVDSS	RDSON	ID
-60V	68mΩ	-4.9A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT- 23-6L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	-60	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -4.5V ¹	-4.9	А	
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.3	Α	
I _{DM}	Pulsed Drain Current ²	-11	Α	
P _D @T _A =25°C	Total Power Dissipation ³	1.3	W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
T_J	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		125	°C/W	
R _{eJC}	Thermal Resistance Junction-Case ¹		80	°C/W	



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.014		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-4.9A		68	85	mΩ
		V _{GS} =-4.5V , I _D =-2.5A		80	110	
V _{GS(th)}	Gate Threshold Voltage	V V 1 050 A	-0.5	-0.8	-1.2	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		3.95		mV/℃
l	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =25℃			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =55℃			-5	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-2.9A		11		S
Q_g	Total Gate Charge (-4.5V)			11	15.4	
Q_gs	Gate-Source Charge	V_{DS} =-30V , V_{GS} =-4.5V , I_{D} =-2.9A		1.4	2.1	nC
Q_gd	Gate-Drain Charge			2.4	3.2	
T _{d(on)}	Turn-On Delay Time			8.5	16	
T _r	Rise Time	V _{DD} =-30V ,		5.8	11	
$T_{d(off)}$	Turn-Off Delay Time	V _{GS} =-4.5V ,		36	65	ns
T _f	Fall Time	R _G =3.3Ω, I _D =-2.9A		5.6	11	
C _{iss}	Input Capacitance			430	560	
Coss	Output Capacitance	V _{DS} =-30V , V _{GS} =0V , f=1MHz		41	66	pF
C _{rss}	Reverse Transfer Capacitance			25	35	

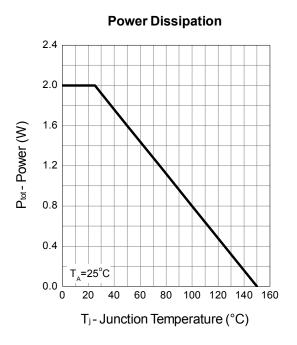
Diode Characteristics

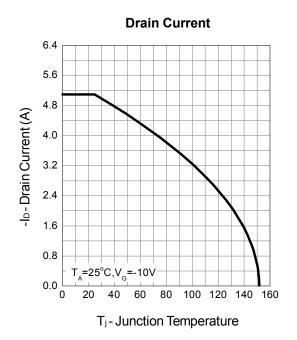
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			-4.9	Α
I _{SM}	Pulsed Source Current ^{2,4}				-11	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1	V
t _{rr}	Reverse Recovery Time	IF=-2.9A , dI/dt=100A/μs ,		20		nS
Q _{rr}	Reverse Recovery Charge	TJ=25℃		19		nC

Note

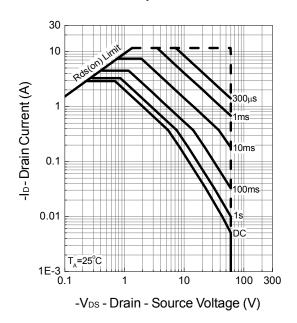
- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3.The power dissipation is limited by 150 $^{\circ}\mathrm{C}^{\circ}$ junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



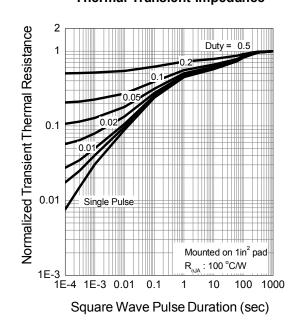




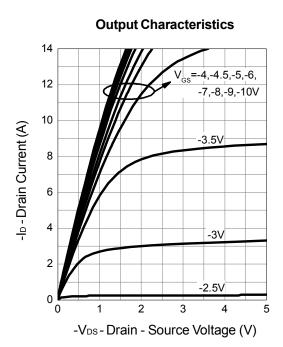
Safe Operation Area

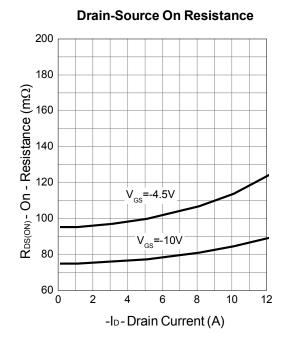


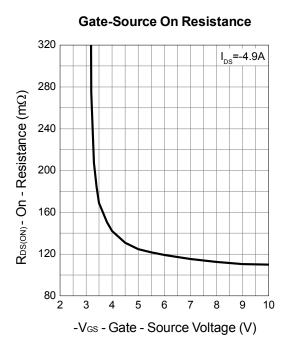
Thermal Transient Impedance

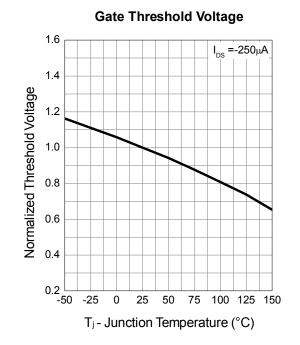






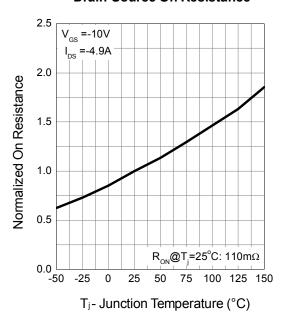




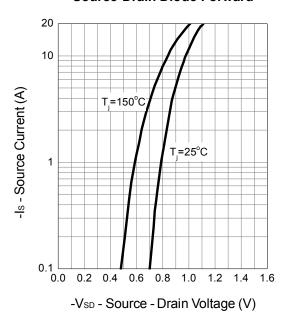




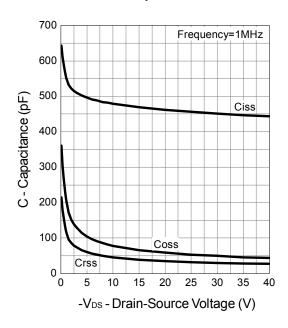
Drain-Source On Resistance



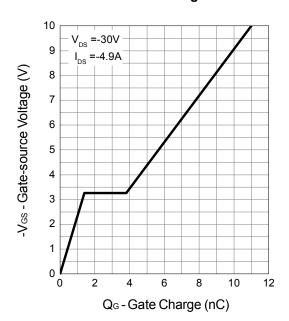
Source-Drain Diode Forward



Capacitance

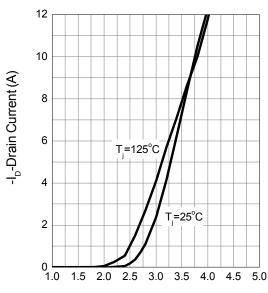


Gate Charge





Transfer Characteristics



 $\text{-V}_{\scriptscriptstyle{\mathsf{GS}}}\text{-}\operatorname{Gate}\text{-}\operatorname{Source}\operatorname{Voltage}$



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